

# Update: High-Temperature Electronics and Testing

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# Outline

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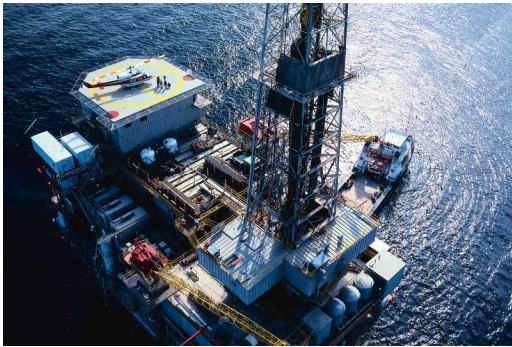
- **Introduction**
- **High-Temperature Electronics at Sandia**
- **High-Temperature Testing Guidelines**
- **What Sandia Can Do**



# Introduction - Why?

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New high-temperature SiC & SOI electronics benefits both sides of the energy equation.



- **Oil and Gas Exploration**

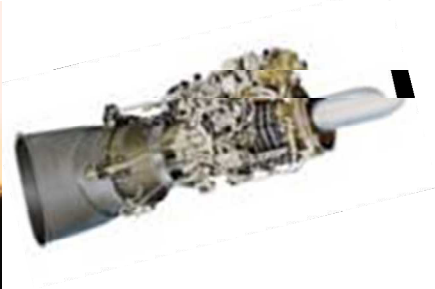
- Deep-offshore GOM wells are hot, 200 – 300 Celsius. Costs >\$100 Mil each!
- On-shore natural gas wells are >17,000 ft.
- Steam injection production is a growing market

- **Geothermal Power Production**

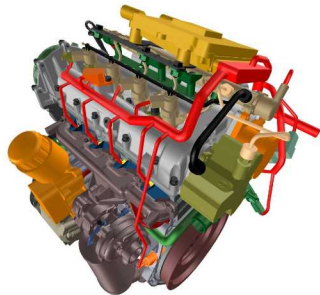
- **Nuclear Power**



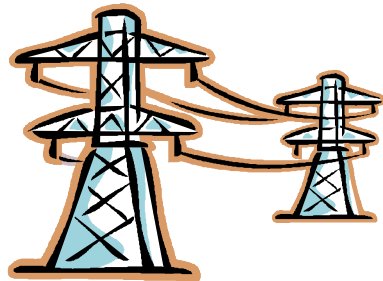
# Introduction - Why?



- **Aircraft saves fuel**
  - Fly by wire (Replace hydraulics and pneumatics with electrical)
  - Distributed controls on the engine
  - 200 to 600 Celsius/44,000 hrs



- **Automobiles saves fuel**
  - Improved hybrids
  - Drive by wire
  - 125 – 180 Celsius /10 years



- **Power grid improvements**
  - Modular controls
  - Reduced cooling fans
  - >150 Celsius – 20kV



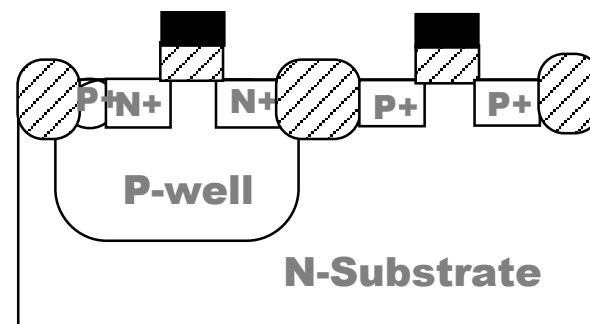
# **Introduction – Common Goals for Using High-Temperature Electronics**

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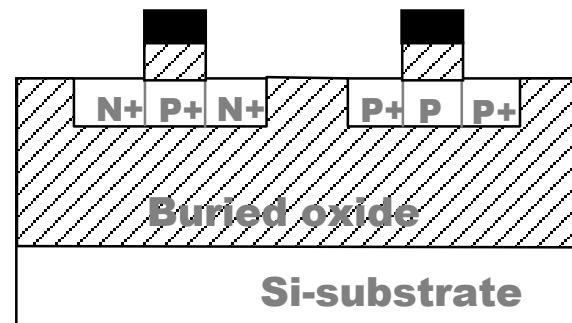
- **Increase temperature capability of electronics**
  - **passively cool electronics**
- **Save volume and space**
  - **Replace active cooling with passive cooling (Example – On an aircraft, to cool 1 kWatt of thermal energy, must add 25 pounds to the aircraft)**
- **Improve power system efficiency**
  - **Eliminate transients and improve current capabilities for electronic systems for  $T > 150$  Celsius.**
- **Reduce thermal hot spots**
- **Increase power density**
- **Increase operating life and reliability**

# Introduction – What Are High Temperature Electronics? SOI Devices

- **Silicon-On-Insulator (SOI)** isolates transistors on an insulating material providing:
  - Isolation reduces leakage currents by ~100 times!
  - Latchup immunity
  - 25% Faster Switching
  - Better isolation for analog and digital on the same die
- SOI is the same process as used for Radiation Hardened silicon



A: Cross-section of bulk CMOS inverter

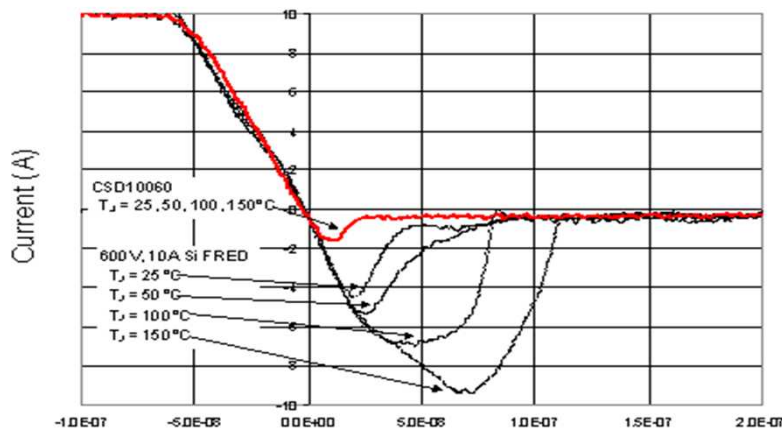


B: Cross-section of a SOI CMOS inverter

**In short, SOI is just a better way to build silicon electronic devices**

# Introduction – What Are High Temperature Electronics? SiC Devices

- SiC has 7 times the voltage breakdown of Si
- SiC has ~3 times the thermal conductivity of Si
- SiC devices are 5 to 10 times smaller than Si
- The smaller SiC power transistor can be operated much faster allowing for smaller passives devices



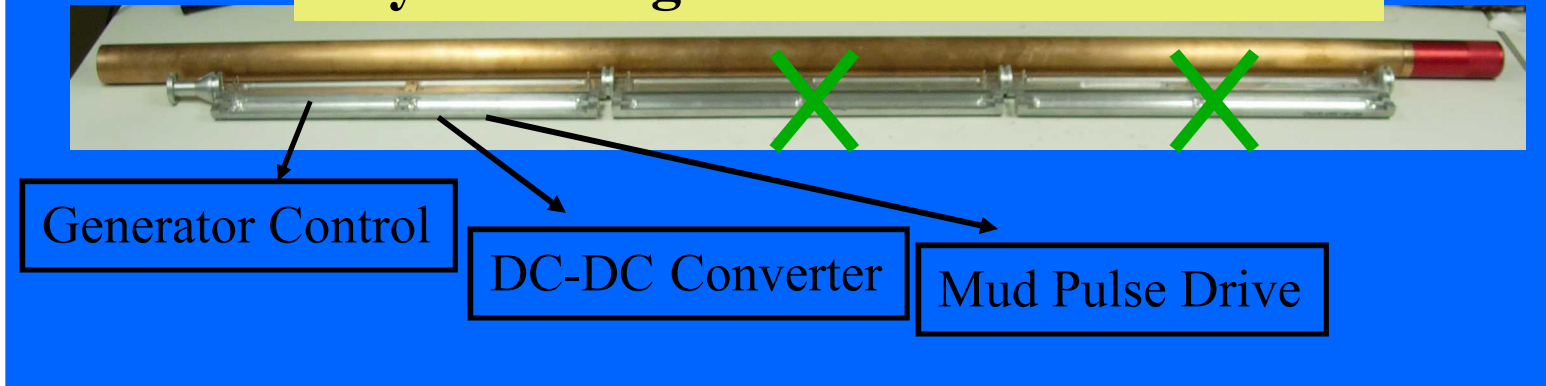
Courtesy Suresh Soni, GTI 2006

Courtesy Anant Agarwal, Cree HiTEC 2006

# Introduction – Advantage of Using SOI and SiC Devices in Applications

- HPHT turbine regulator using HT SOI and SiC electronics
  - 1/3 the size of the conventional 200°C Si switcher
  - Operates up to 250°C+
  - Commercial systems reduce energy loss by 30-50%
- In 3-5 years this SiC technology will dominate the drilling industry power electronics!!!

## Layout Using SOI and SiC Electronics







## High-Temperature Electronics at Sandia - Our Suppliers are the Industry Leaders

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- Below is a short list of the companies Geothermal Research Department is currently working with

***Quartzdyne Inc.***

***Presidio Components, Inc.***

***Paine Electronics***

***Multilayer Prototypes, Inc***

***Kulite Semiconductor Products***

***Honeywell SSCS***

***Weed Instrument Company***

***Cissoid***

***Kemlon Products***

***Electrochemical Systems***

***Semisouth Laboratories***

***Endevco Corp***

***Rockwell Scientific/ GTI***

***Regal Plastic Supply Co.***

***Biotronics***

***Honeywell Richmond***

***Solid State Devices Inc.***


***General Atomics***



# **High-Temperature Electronics at Sandia – Geothermal Research Progress**

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- **Sandia has a complete DAQ 250°C (482°F) tool able to stay in the well indefinitely.**
  - **Long-term demonstration testing with over 17,000 hrs at 193°C**
    - **Complete 48 channel  $\mu$ P tool tested to 250°C**
    - **Currently planning a long-term 225°C demonstration**
  - **Currently testing a 275-300°C tool in Bakersfield, Ca.**
    - **Simple two-data-channel tool**
    - **Planning a long-term 8 week test with a major oil company**
  - **DWD for downhole bit monitoring while drilling at 225°C**
- **We can quickly modify our tool to use almost any electronic component or sensor**



# **High-Temperature Electronics at Sandia – Evaluating New High-Temperature Components**

- **HT PC Board Material**
- **300°C Quartz Crystal**
- **300°C SOI Clock Chip**
- **EEPROM 64K X 16**
- **400°C SiC MEM Pressure Sensor (for aircraft engines)**
- **250°C SiC JFET Normally On**
- **200°C SiC JFET ~Normally Off**



## **High-Temperature Electronics at Sandia - New Components Coming to Geothermal Research by January 2007**

- **8 bit PWM SOI (Automotive)**
- **2K EEPROM SOI (Automotive)**
- **8-Channel, 12-Bit SOI A/D**
- **350°C SOI MEM Pressure Sensor**
- **275°C 8/16 bit SOS HC11  $\mu$ P with ROM (Late Jan)**

# **High-Temperature Electronics at Sandia – Proving Reliability of High-Temperature Electronics and Systems - Long-Term SOI Tool Demonstration**

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**Objective: Demonstrate a microprocessor, multi-channel data collection set of SOI electronics**

**The Coso well was chosen at 193°C. This is the hottest location within the well. We have 750+ days in the well, along with 750 hours at 200°C inside a test oven.**



# **Current Issues with High-Temperature Electronics**

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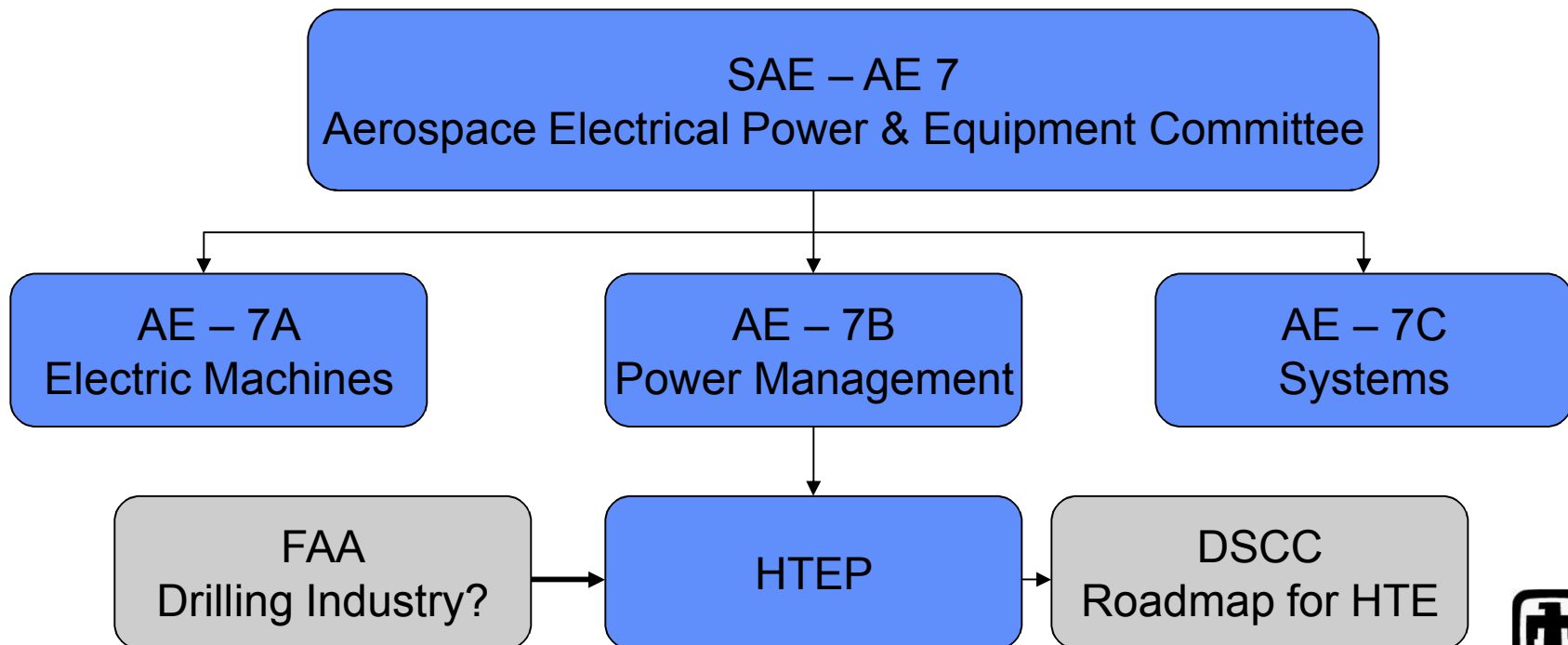
- **Capacitors**
  - Lack of high-voltage, high-capacitance capacitors due to limitations of X7R ceramic
- **Solders/ Interconnects**
  - Lack of high-temperature solders (other than 95.5-2.0-2.5 Pb-Sn-Ag)
- **Packaging (Standard FR4 PCB limited to 175°C)**
  - What is the best approach – MCM ( $\text{Al}_2\text{O}_3$ , AlN substrates) or high-temperature polymer packaging (polyimide)?



## High-Temperature Test Guidelines – Who Is Proposing the Guidelines

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- Defense Supply Center Columbus (DSCC) maintains the military standards for components (MIL-PRF). However, components that are qualified are very expensive.
- High-Temperature Electronics Panel (HTEP) of SAE – AE7 Committee Is Proposing High-Temperature Test guidelines, which will help to establish reliability of high-temperature components and to make them affordable.





## High-Temperature Test Guidelines – Why Have Guidelines

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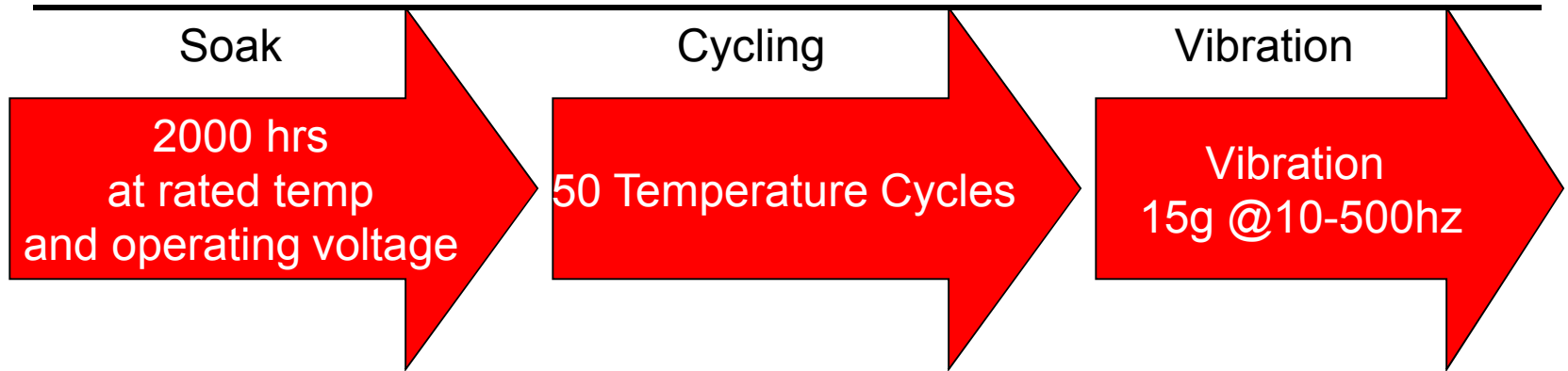
- **Aid component manufacturers in identification of components as high-temperature and reliable**
- **Aid design engineers and system engineers in minimizing qualification testing and development time by using qualified high-temperature electronic components (along with standardized test data from the manufacturer).**
- **Aid end-users of high-temperature systems in identifying products that are built with high-temperature, reliable components and sensors.**



# Suggested Minimum Testing for HT Components and Sensors


(Proposed Guidelines Being Developed by High-Temperature Electronics Panel (HTEP) of Society of Aerospace Engineers (SAE) – AE7 Committee)

Test device is calibrated to manufacturers operating specification



A failed device is any device falling more than 5% outside of the manufacturers specification. A complete set of test data, test devices and procedures must be reported in open publication.

Test device is tested against manufacturers operating specification



## **Suggested Minimum Testing for HT Components and Sensors (cont.)**

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- **Destructive Physical Analysis (DPA) and Visual-Mechanical Examination per MIL-STD-1580**
  - **Verify workmanship, construction and materials in making the component or the sensor**
  - **Show that component is free of unsuitable materials for high-temperature (e.g., 100% Sn) and is defect free.**
  - **Prevent counterfeiting of qualified, high-temperature, high-reliability components**
- **Solderability**
  - **Ensure that reliable interconnects can be made between components and packaging.**



# What Sandia National Labs Can Do

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- There is room for Sandia in HT component development
  - John Witham, 1732 for HT Capacitors
  - Karen Waldrip, 2521 for GaN crystal growth
- There is room for Sandia in component and system-level packaging development
  - The success of future systems is 100% dependent on packaging and interconnects
    - Most applications will use the same devices in die form
    - Robust packaging and reliable interconnects are the key to high-temperature electronic systems.
  - Paul Vianco, 1824 for Solders and die attach
  - Blake Jakaboski, 17152 for HT packaging



## **What Sandia Can Do – Departments 1732 (Frequency Devices) and 1734 (Component Information & Models)**

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- **Component Testing (Electrical, Thermal, Mechanical, Radiation) → 1732, 1734**
- **High Performance Electrical Modeling and Simulation (HPEMS – Xyce, Chile SPICE, etc.) → 1734**
- **Component Modeling (Library of >1800 component models, Model Verification, Model Extraction, Advanced Model Development, etc.) → 1734**
- **Failure Analysis (Electrical Failure Analysis Laboratory, Scanning Electron Microscope Laboratories, Focused Ion Beam System, Optical Microscopy Laboratory, Scanning Probe Microscope Laboratory) → Sandia Site Wide**
- **Reliability and Risk Assessments of Components → 1732, 1734**



## **What Sandia Can Do – Departments 1732 (Frequency Devices) and 1734 (Component Information & Models) (cont.)**

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- **Weapons Reserve COTS Insertion Process (WRCIP – Parts Selection, Procure and Accept, Reliability and Qualification) → 1732, 1734**
- **Development, use and implementation of commercial and Sandia-developed sensors to provide functional sensor sub-systems → 1732**
- **Design and development of clocks, oscillators and sensors for national security applications → 1732**
- **Design, develop and test custom capacitors for national security applications → 1732**



## **What Sandia National Labs Can Do (cont.)**

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- **Geothermal Research Can Do:**
  - **Provide third party test data on components and sensors**
  - **Simulate real world applications within the drilling industry by building complete HT – HR drilling tools**
  - **Provide a list of Sandia suppliers to anyone on request**
  - **Encourage new DOE programs in HT components, sensors and systems.**



# Conclusions

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- High temperature electronics and sensors have potential applications in geothermal, petroleum, aerospace, military and automotive industries after reliability is proven.
- High-temperature testing guidelines are needed to provide a formalized guideline for component manufacturers on high-temperature components and to establish the reliability of high-temperature components for end users.
- High-temperature electronics and components would benefit the energy industry and the national security of the United States.
- Thank you for your time and for your consideration.



# Definitions

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- **SOI – Silicon on Insulator**
- **SOS – Silicon on Sapphire**
- **SiC – Silicon Carbide**
- **μP – microprocessor**
- **EEPROM – electrical erasable programmable read only memory**
- **MEM – micro-electro-mechanical**
- **JFET- Junction Gate Field Effect Transistor**
- **A/D – Analog to Digital**
- **PWM – Pulse Width Modulator**
- **ROM – Read Only Memory**
- **AlN – Aluminum Nitride**
- **Al<sub>2</sub>O<sub>3</sub> – Aluminum Oxide**
- **X7R – Electronic Industry Association (EIA) designation of capacitance change of ±15% from -55°C to +125°C unbiased.**





# COTS Testing, Evaluation and Qualification Resources

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- CALCE – Center for Advanced Life Cycle Engineering  
(<http://www.calce.umd.edu/>)
- DSCC – Defense Supply Center Columbus  
(<http://www.dsccl.dla.mil/>)
- NASA Electronic Parts and Packaging Program (NEPP)  
(<http://nepp.nasa.gov/>)
- Sandia National Laboratories Microsystems Science, Technology & Components (<http://www.sandia.gov/mstc/index.html>)
- Honeywell Solid State Electronics Center (SSEC)  
(<http://www.ssec.honeywell.com/hightemp/>)
- NASA Silicon Carbide Electronics  
(<http://www.grc.nasa.gov/WWW/SiC/index.html>)
- Sandia National Laboratories Microsystems Science, Technology & Components – Electronic Components  
(<http://www.sandia.gov/mstc/products/elect-comp/index.html>)